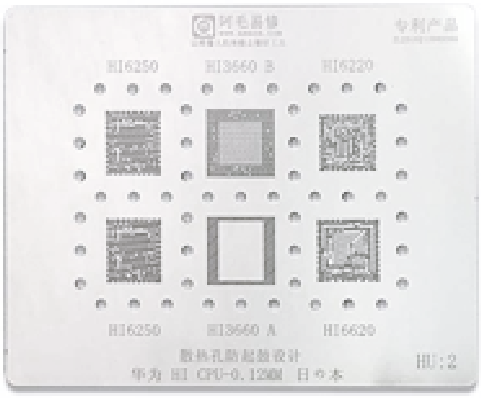

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BGA stencils for Huawei HISilicon CPU (HU: 2) 0.12mm

Product ID: 22173

Price: **12.00 EUR**

Product weight: **0.01 kg**

Description:

BGA stencils for Huawei HISilicon CPU (HU: 2) 0.12mm allow you to reball 6 models: HI6520, HI3660B, HI6220, HI6250, HI3660A, HI6622.

Go to the product

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